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Quarterly Reliability Monitoring Results

Quarters: Q1/2022 to Q4/2023 Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory Assembly reliability labs Based on AEC-Q101 Test		User Part Number					
		BAT32LS-Q					
		Part Description					
		Nexperia DHAM Schottky					
		MCD package					
		Test Conditions	Duration	# Lots	# Quantity	# Rejects	
	TEST				. ,		
	Pre- and Post-Stress						
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below	
		JESD22-A113	,				
		Bake Tamb = $125 ^{\circ}\text{C}$	24 hours				
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours				
# A1	Preconditioning	Reflow soldering	3 cycles	208	9760	0	
# A1		MIL-STD-750-1	,			-	
	HTRB	M1038 Method A					
		Tj = Tjmax, $Vr = 100%$ of max. datasheet					
# B1	Bias	reverse voltage ^[1]	1000 hours	206	9320	0	
# DI	5103	Teverse voltage	1000 110015	200	9320	0	
	тс	JESD22-A104					
# A4	Temperature Cycling	-65 °C to Tjmax, not to exceed 150°C	1000 cycles	53	2400	0	
# A4	Temperature cycling		1000 Cycles	55	2400	0	
	UHAST	JESD22-A118					
# A3 or	Unbiased HAST	Tamb = $130 ^{\circ}$ C, RH = $85 ^{\circ}$					
	Unblased HAST	,	—96 hours	53	2400	0	
		JESD22-A102					
	AC	Tamb = 121 °C, RH = 100 %					
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)					
		150000 4101					
	H3TRB	JESD22-A101					
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of					
# A2 alt	Temperature Reverse Bias		1000 hours	53	2400	0	
		MIL-STD-750 Method 1037					
	IOL	ton = toff, devices powered to insure ΔTj =					
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	49	2560	0	
	RSH	JESD22-A111					
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	n.a.	n.a.	n.a.	
	SD						
# C10	Solderability	J-STD-002		37	1110	0	

The physical limitations of Schottky diodes have to be considered (thermal runaway).
The maximum applied voltage is limited by test chamber set up and does not exceed 115V.

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9320	0	0,46	2,19E+09

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